

# HSF

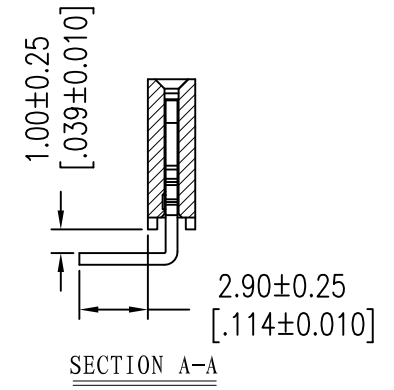
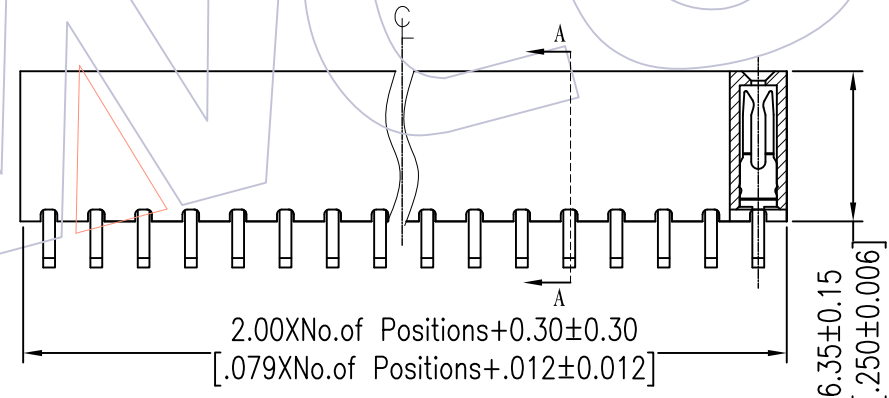
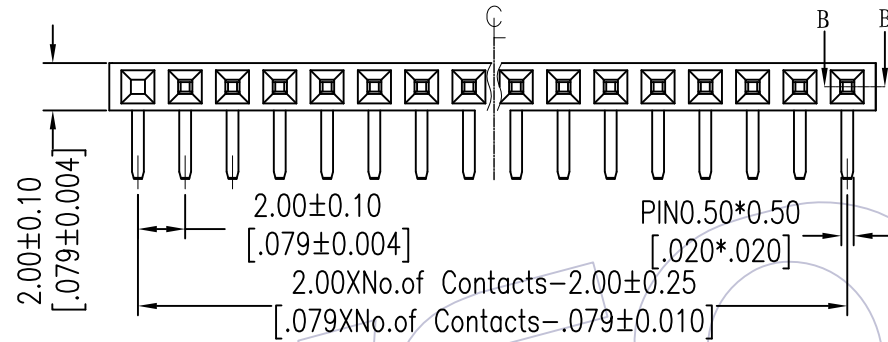
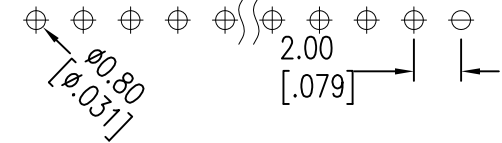
**NOTES:**

Current Rating: 2.0AMP  
 Contact Resistance: 20mΩ Max  
 Withstand Voltage: 500V AC/DC  
 Insulation Resistance: 1000MΩ Min  
 Operation Temperature: -40°C to +105°C

Contact Material: Phosphor Bronze  
 Contact plating: Au Or Sn over Ni  
 Insulator Material: LCP+30%G.F UL94V-0



Recommended P.C.B Layout (Top Side)  
 (PCB BOARD TOLERANCE ±0.05)



## Ordering Information

2263 - 1 XX R XX D Y N T 1

No. of Pins per ROW: 02-40 PIN  
 Contact Plating: G0=Gold Flash  
 G3=10μ"Gold  
 G4=15μ"Gold  
 G5=30μ"Gold  
 S0=Gold Flash/Tin  
 S3=10μ"Gold/Tin  
 S4=15μ"Gold/Tin  
 S5=30μ"Gold/Tin  
 SN=Tin  
 SM=Matte Tin  
 Insulator: D=LCP  
 Packing: T=Tube

Item	Pitch	Mating
Standard	2.00	1215/1220
Alternate		

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	OPERATION		DRAW Wang	DATE	SCALE	FIT	PART NO.
				X.X	±0.40					
A1	2013/03/15	Modify drawing	-----	X.XX	±0.25	CHECK	2013/03/15	UNIT	mm	2263-1XXRXXDYNT1
A0	2012/12/7	NEW	-----	X.XXX	±0.15	APPROVE		SIZE	A4	TITLE: FH2.0mm SINGLE ROW 90° SMT H=6.3
				Angle	± 3°			SHEET	1/1	Customer NO.
				DIM	TOL			PROJ.		